

POLARIS G620 Physical Vapor Deposition System

System Overview

Polaris G620 is a fully automated general PVD sputtering system that supports a wide variety of applications and materials. It has a flexible chamber configuration around a single transfer module and can be configured with up to six modules.



Substrate Size:	150 mm, 200 mm; (100 mm with adapters)
Technology Markets:	IC, Power IC, MEMS, LED, and Advance Packaging
Process Modules:	Up to 6 *
Deposit Material:	Cu, Ti, Ta, Al, AlSi, AlCu, Ni, NiV, Ag, Au, TiW, SiO ₂ , Mo, Si, Ir, Hf, Pt ITO, SiO ₂ , TiO ₂ , HfO ₂ , Ta ₂ O ₅ , TaO _x , TiN, TaN

* See the eVictor GX20 for higher capacity requirements

Processes

- Metal films
- Oxide films
- Through silicon via deposition

Production Advantages

- Excellent temperature and particle control
- High target utilization rate and low operating costs
- Optimized software algorithms and process recipes provide higher throughput and lower cost of operation
- Flexible chamber configuration with up to six process modules, including Degas, Preclean and PVD
- Manual or SMIF load lock ports